

# Product Change Notification - JAON-08BVJU876

**Date:** 12 Jul 2017

**Product Category:** Memory; Power MOSFET Drivers; Interface- Infrared Products; Sigma - Delta A/D Converters; Digital Potentiometers; System D/A Converters; Linear Op Amps; Linear Comparators; Instrumentation Amplifier; Linear Programmable Gain Amplifiers; Capacitive Touch Sensors; 8-bit PIC Microcontrollers; Temperature Sensors

**Notification subject:** CCB 1835 Final Notice: Qualification of CuPdAu bond wire in selected products of the 40K, 42K, 77K, 120K, 150K, 160K and 200K wafer technologies available in 8L SOIC package at MMT assembly site.

**Notification text:** **PCN Status:**  
Final notification

**Microchip Parts Affected:**  
Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**  
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 40K, 42K, 77K, 120K, 150K, 160K and 200K wafer technologies available in 8L SOIC package at MMT assembly site.

**Pre Change:**  
Gold (Au) or Palladium coated copper wire (PdCu) bond wire

**Post Change:**  
Palladium coated copper with gold flash (CuPdAu) bond wire

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	MMT assembly site	MMT assembly site
<b>Wire material</b>	Au wire or PdCu wire	CuPdAu wire
<b>Die attach material</b>	8390A	8390A
<b>Molding compound material</b>	G600V	G600V
<b>Lead frame material</b>	CDA194	CDA194

**Impacts to Data Sheet:**  
None

**Change Impact:**  
None

**Reason for Change:**  
To improve manufacturability by qualifying Palladium coated copper with gold flash (CuPdAu) bond wire.

**Change Implementation Status:**  
In Progress

**Estimated First Ship Date:**  
April 20, 2017 (date code: 1716)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	January 2016				- >	March 2017					April 2017			
	01	02	03	04		09	10	11	12	13	14	15	16	17
Initial PCN Issue Date		X												
Qual Report Availability								X						
Final PCN Issue Date								X						
Implementation Date												X		

**Method to Identify Change:**  
Traceability code

**Qualification Report:**  
Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

**Revision History:**  
**January 13, 2016:** Issued initial notification.  
**March 20, 2017:** Issued final notification. Attached the qualification report. Revised the estimated first ship date from April 20, 2016 to April 16, 2017. Updated subject and description to include selected products of the 40K, 42K, 77K, 120K, 150K and 160K wafer technologies.  
**April 8, 2017:** Updated affected CPN list.  
**July 12, 2017:** Update the Qualification report to correct a typographical error.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):** [PCN\\_JAON-08BVJU876\\_Qual Report.pdf](#)  
[PCN\\_JAON-08BVJU876\\_Affected\\_CPN.pdf](#)  
[PCN\\_JAON-08BVJU876\\_Affected\\_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

**Terms and Conditions:**

If you wish to change your product/process change notification (PCN) profile please log on to our website at [http://\\*/PCN](http://*/PCN) sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to [microchipDIRECT](#) and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

JAON-08BVJU876 - CCB 1835 Final Notice: Qualification of CuPdAu bond wire in selected products of the 40K, 42K, 77K, 120K, 150K, 160K and 200K wafer technologies available in 8L SOIC package at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
24AA01/SN
24AA01-I/SN
24AA01T/SN
24AA01T-I/SN
24AA02/SN
24AA02-I/SN
24AA02T/SN
24AA02T-I/SN
24AA04/SN
24AA044-E/SN
24AA044-I/SN
24AA044T-E/SN
24AA044T-I/SN
24AA04H-I/SN
24AA04HT-I/SN
24AA04-I/SN
24AA04T/SN
24AA04T-I/SN
24AA08/SN
24AA08H-I/SN
24AA08HT-I/SN
24AA08-I/SN
24AA08T/SN
24AA08T-I/SN
24AA128-I/SN
24AA128T-I/SN
24AA128T-I/SNRVF
24AA16-E/SN
24AA16H-I/SN
24AA16HT-I/SN
24AA16-I/SN
24AA16-I/SNB22
24AA16T-E/SN
24AA16T-I/SN
24AA256-E/SN
24AA256-I/SN
24AA256-I/SN104
24AA256-I/SNRVE
24AA256T-E/SN
24AA256T-I/SN
24AA256T-I/SN104
24AA256T-I/SN105
24AA256T-I/SNRVE

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
24AA256UID-I/SN
24AA256UIDT-I/SN
24AA32AF-I/SN
24AA32AFT-I/SN
24AA32A-I/SN
24AA32A-I/SNRVE
24AA32AT-I/SN
24AA32AT-I/SNRVE
24AA64/SN
24AA64-E/SN
24AA64F-I/SN
24AA64FT-I/SN
24AA64-I/SN
24AA64-I/SN101
24AA64T/SN
24AA64T-E/SN
24AA64T-I/SN
24AA64T-I/SN101
24AA64T-I/SNB79
24FC128-E/SN
24FC128-I/SN
24FC128T-E/SN
24FC128T-I/SN
24FC256-E/SN
24FC256-I/SN
24FC256T-E/SN
24FC256T-I/SN
24FC64F-I/SN
24FC64FT-I/SN
24FC64-I/SN
24FC64T-I/SN
24LC01B-E/SN
24LC01B-I/SN
24LC01BT-E/SN
24LC01BT-I/SN
24LC02B/SN
24LC02B-E/SN
24LC02B-I/SN
24LC02BT/SN
24LC02BT/SNA31
24LC02BT-E/SN
24LC02BT-I/SN
24LC04B/SN

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
24LC04B-E/SN
24LC04BH-E/SN
24LC04BH-I/SN
24LC04BHT-E/SN
24LC04BHT-I/SN
24LC04B-I/SN
24LC04BT/SN
24LC04BT-E/SN
24LC04BT-I/SN
24LC08B/SN
24LC08B-E/SN
24LC08BH-E/SN
24LC08BH-I/SN
24LC08BHT-E/SN
24LC08BHT-I/SN
24LC08B-I/SN
24LC08B-I/SNA27
24LC08B-I/SNRVE
24LC08BT/SN
24LC08BT/SNRVE
24LC08BT-E/SN
24LC08BT-I/SN
24LC08BT-I/SNA23
24LC08BT-I/SNA27
24LC08BT-I/SNRVE
24LC128-E/SN
24LC128-I/SN
24LC128-I/SNRVE
24LC128-I/SNRVF
24LC128T-E/SN
24LC128T-I/SN
24LC128T-I/SNRVE
24LC128T-I/SNRVF
24LC16B/SN
24LC16B-E/SN
24LC16B-E/SNA26
24LC16BH-E/SN
24LC16BH-I/SN
24LC16BHT-E/SN
24LC16BHT-I/SN
24LC16B-I/SN
24LC16B-M/SN
24LC16BT/SN

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PCN_JAON-08BVJU876
CATALOG_PART_NBR
24LC16BT/SNA31
24LC16BT/SNRVE
24LC16BT-E/SN
24LC16BT-E/SNA26
24LC16BT-I/SN
24LC16BT-I/SNRVE
24LC16BT-M/SN
24LC21/SN
24LC21A/SN
24LC21A-I/SN
24LC21A-I/SN100
24LC21AT/SN
24LC21AT-I/SN
24LC21AT-I/SN100
24LC21-I/SN
24LC21T/SN
24LC21T-I/SN
24LC22A-I/SN
24LC22AT-I/SN
24LC256-E/SN
24LC256-I/SN
24LC256-I/SNRVE
24LC256T-E/SN
24LC256T-E/SNRVE
24LC256T-I/SN
24LC256T-I/SNRVE
24LC256T-I/SNRVF
24LC32A/SN
24LC32A-E/SN
24LC32AF-E/SN
24LC32AF-I/SN
24LC32AFT-E/SN
24LC32AFT-I/SN
24LC32A-I/SN
24LC32A-I/SNA27
24LC32A-I/SNRVE
24LC32AT/SN
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24LC32AT-I/SN
24LC32AT-I/SNA23
24LC32AT-I/SNA27
24LC32AT-I/SNRVE
24LC64-E/SN

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PCN_JAON-08BVJU876
CATALOG_PART_NBR
24LC64F-E/SN
24LC64F-I/SN
24LC64FT-E/SN
24LC64FT-I/SN
24LC64-I/SN
24LC64-I/SN100
24LC64-I/SNRVE
24LC64T-E/SN
24LC64T-E/SNA31
24LC64T-I/SN
24LC64T-I/SN100
24LC64T-I/SNRVE
24LCS21A/SN
24LCS21A-I/SN
24LCS21AT/SN
24LCS21AT-I/SN
24LCS22A-I/SN
24LCS22AT-I/SN
25AA080/SN
25AA080A-I/SN
25AA080AT-I/SN
25AA080B-I/SN
25AA080BT-I/SN
25AA080BT-I/SNB21
25AA080C-I/SN
25AA080CT-I/SN
25AA080D-I/SN
25AA080DT-I/SN
25AA080-I/SN
25AA080T/SN
25AA080T-I/SN
25AA128-E/SN
25AA128-I/SN
25AA128T-E/SN
25AA128T-I/SN
25AA128T-I/SNRVA
25AA160/SN
25AA160A-I/SN
25AA160A-I/SN103
25AA160AT-I/SN
25AA160AT-I/SN103
25AA160B-I/SN
25AA160BT-I/SN

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PCN_JAON-08BVJU876
CATALOG_PART_NBR
25AA160C-I/SN
25AA160CT-I/SN
25AA160D-E/SN
25AA160D-I/SN
25AA160DT-E/SN
25AA160DT-I/SN
25AA160-I/SN
25AA160T/SN
25AA160T-I/SN
25AA256-E/SN
25AA256-I/SN
25AA256T-E/SN
25AA256T-I/SN
25AA256T-I/SNB31
25AA320A-I/SN
25AA320A-I/SNB22
25AA320AT-I/SN
25AA320AT-I/SNB22
25AA512-I/SN
25AA512T-I/SN
25AA640A-E/SN
25AA640A-I/SN
25AA640AT-E/SN
25AA640AT-I/SN
25AA640AT-I/SNB23
25C080/SN
25C080-E/SN
25C080-I/SN
25C080T/SN
25C080T-E/SN
25C080T-I/SN
25C160/SN
25C160-E/SN
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25C160T/SN
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25LC080/SN
25LC080A-E/SN
25LC080A-H/SN
25LC080A-I/SN
25LC080AT-E/SN
25LC080AT-H/SN

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PCN_JAON-08BVJU876
CATALOG_PART_NBR
25LC080AT-I/SN
25LC080B-E/SN
25LC080B-I/SN
25LC080BT-E/SN
25LC080BT-I/SN
25LC080C-E/SN
25LC080C-H/SN
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25LC080CT-E/SN
25LC080CT-H/SN
25LC080CT-I/SN
25LC080D-E/SN
25LC080D-H/SN
25LC080D-I/SN
25LC080DT-E/SN
25LC080DT-H/SN
25LC080DT-I/SN
25LC080-I/SN
25LC080T/SN
25LC080T-I/SN
25LC128-E/SN
25LC128-H/SN
25LC128-I/SN
25LC128T-E/SN
25LC128T-H/SN
25LC128T-I/SN
25LC160/SN
25LC160A-E/SN
25LC160A-I/SN
25LC160AT-E/SN
25LC160AT-I/SN
25LC160B-E/SN
25LC160B-I/SN
25LC160BT-E/SN
25LC160BT-I/SN
25LC160C-E/SN
25LC160C-H/SN
25LC160C-I/SN
25LC160CT-E/SN
25LC160CT-H/SN
25LC160CT-I/SN
25LC160D-E/SN
25LC160D-H/SN



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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
25LC160D-I/SN
25LC160DT-E/SN
25LC160DT-E/SN16KA21
25LC160DT-H/SN
25LC160DT-I/SN
25LC160-I/SN
25LC160T/SN
25LC160T-I/SN
25LC256-E/SN
25LC256-H/SN
25LC256-I/SN
25LC256T-E/SN
25LC256T-H/SN
25LC256T-I/SN
25LC320A-E/SN
25LC320A-H/SN
25LC320A-I/SN
25LC320AT-E/SN
25LC320AT-H/SN
25LC320AT-I/SN
25LC512-E/SN
25LC512-I/SN
25LC512-M/SN
25LC512T-E/SN
25LC512T-I/SN
25LC512T-M/SN
25LC640A-E/SN
25LC640A-H/SN
25LC640A-I/SN
25LC640A-M/SN
25LC640AT-E/SN
25LC640AT-H/SN
25LC640AT-I/SN
25LC640AT-M/SN
34AA04-E/SN
34AA04-I/SN
34AA04T-E/SN
34AA04T-I/SN
93AA46/SN
93AA46AE48-I/SN
93AA46AE48T-I/SN
93AA46A-I/SN
93AA46AT-I/SN

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PCN_JAON-08BVJU876
CATALOG_PART_NBR
93AA46AX-I/SN
93AA46AXT-I/SN
93AA46B-I/SN
93AA46BT-I/SN
93AA46BX-I/SN
93AA46BXT-I/SN
93AA46C-I/SN
93AA46CT-I/SN
93AA46CX-I/SN
93AA46CXT-I/SN
93AA46-I/SN
93AA46T/SN
93AA46T-I/SN
93AA56/SN
93AA56A-I/SN
93AA56AT-I/SN
93AA56AX-I/SN
93AA56AXT-I/SN
93AA56B-I/SN
93AA56BT-I/SN
93AA56BX-I/SN
93AA56BXT-I/SN
93AA56C-I/SN
93AA56CT-I/SN
93AA56CX-I/SN
93AA56CXT-I/SN
93AA56-I/SN
93AA56T/SN
93AA56T-I/SN
93AA66/SN
93AA66A-I/SN
93AA66AT-I/SN
93AA66AX-I/SN
93AA66AXT-I/SN
93AA66B-I/SN
93AA66BT-I/SN
93AA66BX-I/SN
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93AA66C-I/SN
93AA66CT-I/SN
93AA66CX-I/SN
93AA66CXT-I/SN
93AA66-I/SN

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
93AA66T/SN
93AA66T-I/SN
93AA66X/SN
93AA66XT/SN
93AA76A-I/SN
93AA76AT-I/SN
93AA76B-I/SN
93AA76BT-I/SN
93AA76C-I/SN
93AA76CT-I/SN
93AA86A-I/SN
93AA86AT-I/SN
93AA86B-I/SN
93AA86BT-I/SN
93AA86C-I/SN
93AA86CT-I/SN
93C46A-E/SN
93C46A-I/SN
93C46AT-E/SN
93C46AT-I/SN
93C46AX-E/SN
93C46AX-I/SN
93C46AXT-E/SN
93C46AXT-I/SN
93C46B/SN
93C46B-E/SN
93C46B-I/SN
93C46BT/SN
93C46BT-E/SN
93C46BT-I/SN
93C46BX/SN
93C46BX-E/SN
93C46BX-I/SN
93C46BXT/SN
93C46BXT-E/SN
93C46BXT-I/SN
93C46C-E/SN
93C46C-I/SN
93C46CT-E/SN
93C46CT-I/SN
93C56A-E/SN
93C56A-I/SN
93C56AT-E/SN

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
93C56AT-I/SN
93C56B-E/SN
93C56B-I/SN
93C56BT-E/SN
93C56BT-I/SN
93C56C-E/SN
93C56C-I/SN
93C56CT-E/SN
93C56CT-I/SN
93C56-E/SN
93C56T-E/SN
93C66A-E/SN
93C66A-I/SN
93C66AT-E/SN
93C66AT-I/SN
93C66B-E/SN
93C66B-I/SN
93C66BT-E/SN
93C66BT-I/SN
93C66C-E/SN
93C66C-I/SN
93C66CT-E/SN
93C66CT-I/SN
93C66-E/SN
93C66T-E/SN
93C76C-E/SN
93C76C-I/SN
93C76CT-E/SN
93C76CT-I/SN
93C86C-E/SN
93C86C-I/SN
93C86CT-E/SN
93C86CT-I/SN
93LC46/SN
93LC46A/SN
93LC46A-E/SN
93LC46A-I/SN
93LC46AT/SN
93LC46AT-E/SN
93LC46AT-I/SN
93LC46AX/SN
93LC46AX-E/SN
93LC46AX-I/SN

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
93LC46AXT/SN
93LC46AXT-E/SN
93LC46AXT-I/SN
93LC46B/SN
93LC46B-E/SN
93LC46B-I/SN
93LC46BT/SN
93LC46BT-E/SN
93LC46BT-I/SN
93LC46BT-I/SND32
93LC46BX/SN
93LC46BX-E/SN
93LC46BX-I/SN
93LC46BXT/SN
93LC46BXT-E/SN
93LC46BXT-I/SN
93LC46C-E/SN
93LC46C-I/SN
93LC46CT-E/SN
93LC46CT-I/SN
93LC46CX-E/SN
93LC46CX-I/SN
93LC46CXT-E/SN
93LC46CXT-I/SN
93LC46-I/SN
93LC46T/SN
93LC46T-I/SN
93LC46X/SN
93LC46X-I/SN
93LC46XT/SN
93LC46XT-I/SN
93LC56/SN
93LC56A/SN
93LC56A-E/SN
93LC56A-I/SN
93LC56AT/SN
93LC56AT-E/SN
93LC56AT-I/SN
93LC56AX-E/SN
93LC56AX-I/SN
93LC56AXT-E/SN
93LC56AXT-I/SN
93LC56B/SN

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
93LC56B-E/SN
93LC56B-I/SN
93LC56BT/SN
93LC56BT-E/SN
93LC56BT-I/SN
93LC56BX/SN
93LC56BX-E/SN
93LC56BX-I/SN
93LC56BXT/SN
93LC56BXT-E/SN
93LC56BXT-I/SN
93LC56C-E/SN
93LC56C-I/SN
93LC56CT-E/SN
93LC56CT-I/SN
93LC56CX-E/SN
93LC56CX-I/SN
93LC56CXT-E/SN
93LC56CXT-I/SN
93LC56-I/SN
93LC56T/SN
93LC56T-I/SN
93LC56X/SN
93LC66/SN
93LC66A/SN
93LC66A-E/SN
93LC66A-I/SN
93LC66AT/SN
93LC66AT-E/SN
93LC66AT-I/SN
93LC66AX/SN
93LC66AX-E/SN
93LC66AX-I/SN
93LC66AXT-E/SN
93LC66AXT-I/SN
93LC66B/SN
93LC66B-E/SN
93LC66B-I/SN
93LC66B-I/SN15K
93LC66BT/SN
93LC66BT-E/SN
93LC66BT-I/SN
93LC66BT-I/SN15K

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
93LC66BX/SN
93LC66BX-E/SN
93LC66BX-I/SN
93LC66BXT-E/SN
93LC66BXT-I/SN
93LC66C-E/SN
93LC66C-I/SN
93LC66CT-E/SN
93LC66CT-I/SN
93LC66CX-E/SN
93LC66CX-I/SN
93LC66CXT-E/SN
93LC66CXT-I/SN
93LC66-I/SN
93LC66T/SN
93LC66T-I/SN
93LC66X/SN
93LC66X-I/SN
93LC66XT-I/SN
93LC76A-E/SN
93LC76A-I/SN
93LC76AT-E/SN
93LC76AT-I/SN
93LC76B-E/SN
93LC76B-I/SN
93LC76BT-E/SN
93LC76BT-I/SN
93LC76C-E/SN
93LC76C-I/SN
93LC76CT-E/SN
93LC76CT-I/SN
93LC86A-E/SN
93LC86A-I/SN
93LC86AT-E/SN
93LC86AT-I/SN
93LC86B-E/SN
93LC86B-I/SN
93LC86BT-E/SN
93LC86BT-I/SN
93LC86C-E/SN
93LC86C-I/SN
93LC86CT-E/SN
93LC86CT-I/SN

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
HA1100/SN
HA1599-E/SN
HA1599T-E/SN
HA688-I/SN
HA688T-I/SN
HA7600-I/SN
HA7600T-I/SN
MCP14E10-E/SN
MCP14E10T-E/SN
MCP14E11-E/SN
MCP14E11T-E/SN
MCP14E6-E/SN
MCP14E6T-E/SN
MCP14E7-E/SN
MCP14E7T-E/SN
MCP14E8-E/SN
MCP14E8T-E/SN
MCP14E9-E/SN
MCP14E9T-E/SN
MCP2122-E/SN
MCP2122T-E/SN
MCP3422A0-E/SN
MCP3422A0T-E/SN
MCP3422A1-E/SN
MCP3422A1T-E/SN
MCP3422A2-E/SN
MCP3422A2T-E/SN
MCP3422A3-E/SN
MCP3422A3T-E/SN
MCP3422A4-E/SN
MCP3422A4T-E/SN
MCP3422A5-E/SN
MCP3422A5T-E/SN
MCP3422A6-E/SN
MCP3422A6T-E/SN
MCP3422A7-E/SN
MCP3422A7T-E/SN
MCP3426A0-E/SN
MCP3426A0T-E/SN
MCP3426A1-E/SN
MCP3426A1T-E/SN
MCP3426A2-E/SN
MCP3426A2T-E/SN



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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
MCP3426A3-E/SN
MCP3426A3T-E/SN
MCP3426A4-E/SN
MCP3426A4T-E/SN
MCP3426A5-E/SN
MCP3426A5T-E/SN
MCP3426A6-E/SN
MCP3426A6T-E/SN
MCP3426A7-E/SN
MCP3426A7T-E/SN
MCP4011-103E/SN
MCP4011-202E/SN
MCP4011-502E/SN
MCP4011-503E/SN
MCP4011T-103E/SN
MCP4011T-202E/SN
MCP4011T-502E/SN
MCP4011T-503E/SN
MCP4021-103E/SN
MCP4021-202E/SN
MCP4021-502E/SN
MCP4021-503E/SN
MCP4021T-103E/SN
MCP4021T-202E/SN
MCP4021T-502E/SN
MCP4021T-503E/SN
MCP41010-E/SN
MCP41010-I/SN
MCP41010T-E/SN
MCP41010T-I/SN
MCP4801-E/SN
MCP4801T-E/SN
MCP4811-E/SN
MCP4811T-E/SN
MCP4821-E/SN
MCP4821T-E/SN
MCP4901-E/SN
MCP4901T-E/SN
MCP4911-E/SN
MCP4911T-E/SN
MCP4921-E/SN
MCP4921T-E/SN
MCP6002-E/SN

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
MCP6002-I/SN
MCP6002T-E/SN
MCP6002T-I/SN
MCP6022-E/SN
MCP6022-I/SN
MCP6022T-E/SN
MCP6022T-I/SN
MCP602-E/SN
MCP602-I/SN
MCP602T-E/SN
MCP602T-I/SN
MCP6042-E/SN
MCP6042-I/SN
MCP6042T-E/SN
MCP6042T-I/SN
MCP6051-E/SN
MCP6051T-E/SN
MCP6052-E/SN
MCP6052T-E/SN
MCP6061-E/SN
MCP6061T-E/SN
MCP6062-E/SN
MCP6062T-E/SN
MCP6071-E/SN
MCP6071T-E/SN
MCP6072-E/SN
MCP6072T-E/SN
MCP6142-E/SN
MCP6142-I/SN
MCP6142T-E/SN
MCP6142T-I/SN
MCP6271-E/SN
MCP6271T-E/SN
MCP6272-E/SN
MCP6272T-E/SN
MCP6273-E/SN
MCP6273T-E/SN
MCP6281-E/SN
MCP6281T-E/SN
MCP6282-E/SN
MCP6282T-E/SN
MCP6283-E/SN
MCP6283T-E/SN

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
MCP6292-E/SN
MCP6292T-E/SN
MCP6402-E/SN
MCP6402-H/SN
MCP6402T-E/SN
MCP6402T-H/SN
MCP6407-H/SN
MCP6407T-H/SN
MCP6422-E/SN
MCP6422T-E/SN
MCP6472-E/SN
MCP6472T-E/SN
MCP6482-E/SN
MCP6482T-E/SN
MCP6492-E/SN
MCP6492T-E/SN
MCP6541-E/SN
MCP6541-I/SN
MCP6541T-E/SN
MCP6541T-I/SN
MCP6542-E/SN
MCP6542-I/SN
MCP6542T-E/SN
MCP6542T-I/SN
MCP6543-E/SN
MCP6543-I/SN
MCP6543T-E/SN
MCP6543T-I/SN
MCP6546-E/SN
MCP6546-I/SN
MCP6546T-E/SN
MCP6546T-I/SN
MCP6548-E/SN
MCP6548-I/SN
MCP6548T-E/SN
MCP6548T-I/SN
MCP6L02T-E/SN
MCP6L2T-E/SN
MCP6L71T-E/SN
MCP6L72T-E/SN
MCP6L92T-E/SN
MCP6N11-001E/SN
MCP6N11-002E/SN

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
MCP6N11-005E/SN
MCP6N11-010E/SN
MCP6N11-100E/SN
MCP6N11T-001E/SN
MCP6N11T-002E/SN
MCP6N11T-005E/SN
MCP6N11T-010E/SN
MCP6N11T-100E/SN
MCP6S21-I/SN
MCP6S21T-I/SN
MCP6S92-E/SN
MCP6S92T-E/SN
MCV08A-I/SN
MTCH112-I/SN
MTCH112T-I/SN
PIC12C508A-04/SN
PIC12C508A-04/SN208
PIC12C508A-04E/SN
PIC12C508A-04I/SN
PIC12C508AT-04/SN
PIC12C508AT-04/SN208
PIC12C508AT-04/SN219
PIC12C508AT-04E/SN
PIC12C508AT-04I/SN
PIC12C508AT-04I/SN077
PIC12C508AT-04I/SN123
PIC12C508AT-04I/SN221
PIC12C508AT-04I/SN231
PIC12C509A-04/SN
PIC12C509A-04/SN035
PIC12C509A-04E/SN
PIC12C509A-04I/SN
PIC12C509A-04I/SNC09
PIC12C509AT-04/SN
PIC12C509AT-04E/SN
PIC12C509AT-04I/SN
PIC12F1571-E/SN
PIC12F1571-I/SN
PIC12F1571-I/SN030
PIC12F1571-I/SN032
PIC12F1571T-E/SN
PIC12F1571T-I/SN
PIC12F1571T-I/SN030

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
PIC12F1571T-I/SN032
PIC12F1572-E/SN
PIC12F1572-I/SN
PIC12F1572-I/SNC01
PIC12F1572T-E/SN
PIC12F1572T-E/SN020
PIC12F1572T-I/SN
PIC12F1572T-I/SN020
PIC12F1572T-I/SNC01
PIC12F1612-E/SN
PIC12F1612-I/SN
PIC12F1612T-I/SN
PIC12F1822-E/SN
PIC12F1822-E/SN027
PIC12F1822-E/SN029
PIC12F1822-E/SN030
PIC12F1822-E/SN031
PIC12F1822-E/SN032
PIC12F1822-E/SN033
PIC12F1822-E/SN041
PIC12F1822-E/SN048
PIC12F1822-E/SNC07
PIC12F1822-I/SN
PIC12F1822-I/SN028
PIC12F1822-I/SN035
PIC12F1822-I/SN045
PIC12F1822-I/SNC04
PIC12F1822-I/SNC08
PIC12F1822-I/SNC09
PIC12F1822-I/SNC11
PIC12F1822-I/SNC12
PIC12F1822-I/SNC15
PIC12F1822T-E/SN
PIC12F1822T-E/SN040
PIC12F1822T-E/SN042
PIC12F1822T-E/SN046
PIC12F1822T-E/SN048
PIC12F1822T-E/SNC07
PIC12F1822T-I/SN
PIC12F1822T-I/SN020
PIC12F1822T-I/SN025
PIC12F1822T-I/SN026
PIC12F1822T-I/SN039

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
PIC12F1822T-I/SN044
PIC12F1822T-I/SN047
PIC12F1822T-I/SN049
PIC12F1822T-I/SNC04
PIC12F1822T-I/SNC08
PIC12F1822T-I/SNC09
PIC12F1822T-I/SNC11
PIC12F1822T-I/SNC12
PIC12F1822T-I/SNC15
PIC12F1840-E/SN
PIC12F1840-H/SN
PIC12F1840-I/SN
PIC12F1840-I/SN023
PIC12F1840-I/SN025
PIC12F1840-I/SNC02
PIC12F1840T-E/SN
PIC12F1840T-H/SN
PIC12F1840T-I/SN
PIC12F1840T-I/SN023
PIC12F1840T-I/SN025
PIC12F1840T-I/SNC02
PIC12F508-E/SN
PIC12F508-I/SN
PIC12F508-I/SN038
PIC12F508T-E/SN
PIC12F508T-E/SN079
PIC12F508T-I/SN
PIC12F508T-I/SN020
PIC12F508T-I/SN025
PIC12F508T-I/SN040
PIC12F508T-I/SN045
PIC12F508T-I/SN056
PIC12F508T-I/SN066
PIC12F508T-I/SN073
PIC12F509-E/SN
PIC12F509-E/SN055
PIC12F509-I/SN
PIC12F509-I/SN051
PIC12F509T-E/SN
PIC12F509T-E/SN052
PIC12F509T-E/SN055
PIC12F509T-I/SN
PIC12F509T-I/SN047

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
PIC12F509T-I/SN048
PIC12F509T-I/SN051
PIC12F509T-I/SN058
PIC12F510-E/SN
PIC12F510-I/SN
PIC12F510-I/SNC06
PIC12F510T-E/SN
PIC12F510T-E/SN070
PIC12F510T-I/SN
PIC12F510T-I/SN041
PIC12F510T-I/SN051
PIC12F510T-I/SN058
PIC12F510T-I/SN064
PIC12F510T-I/SN065
PIC12F510T-I/SN071
PIC12F510T-I/SN073
PIC12F510T-I/SN074
PIC12F510T-I/SN075
PIC12F510T-I/SN077
PIC12F510T-I/SN078
PIC12F510T-I/SN079
PIC12F510T-I/SNC02
PIC12F519-E/SN
PIC12F519-I/SN
PIC12F519-I/SN039
PIC12F519-I/SN041
PIC12F519T-E/SN
PIC12F519T-I/SN
PIC12F519T-I/SN025
PIC12F519T-I/SN028
PIC12F519T-I/SN029
PIC12F519T-I/SN030
PIC12F519T-I/SN031
PIC12F519T-I/SN033
PIC12F519T-I/SN035
PIC12F519T-I/SN037
PIC12F519T-I/SN039
PIC12F519T-I/SN040
PIC12F519T-I/SN041
PIC12F519T-I/SN042
PIC12F519T-I/SN044
PIC12F519T-I/SN047
PIC12F609-E/SN

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
PIC12F609-I/SN
PIC12F609T-E/SN
PIC12F609T-I/SN
PIC12F609T-I/SN027
PIC12F615-E/SN
PIC12F615-H/SN
PIC12F615-I/SN
PIC12F615-I/SN076
PIC12F615-I/SN083
PIC12F615T-E/SN
PIC12F615T-E/SN028
PIC12F615T-H/SN077
PIC12F615T-I/SN
PIC12F615T-I/SN020
PIC12F615T-I/SN043
PIC12F615T-I/SN051
PIC12F615T-I/SN057
PIC12F615T-I/SN058
PIC12F615T-I/SN071
PIC12F615T-I/SN076
PIC12F615T-I/SN079
PIC12F615T-I/SN083
PIC12F617-E/SN
PIC12F617-E/SN020
PIC12F617-E/SN031
PIC12F617-E/SN033
PIC12F617-E/SN034
PIC12F617-I/SN
PIC12F617-I/SN020
PIC12F617-I/SN021
PIC12F617-I/SN030
PIC12F617-I/SN032
PIC12F617-I/SN042
PIC12F617-I/SN047
PIC12F617-I/SN053
PIC12F617-I/SNAU
PIC12F617-I/SNC15
PIC12F617T-E/SN
PIC12F617T-E/SN020
PIC12F617T-E/SN024
PIC12F617T-E/SN026
PIC12F617T-E/SN027
PIC12F617T-E/SN031



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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
PIC12F617T-E/SN033
PIC12F617T-E/SN034
PIC12F617T-E/SN036
PIC12F617T-E/SN037
PIC12F617T-E/SN050
PIC12F617T-E/SN051
PIC12F617T-E/SN052
PIC12F617T-E/SN055
PIC12F617T-E/SN067
PIC12F617T-E/SN071
PIC12F617T-I/SN
PIC12F617T-I/SN020
PIC12F617T-I/SN021
PIC12F617T-I/SN022
PIC12F617T-I/SN023
PIC12F617T-I/SN025
PIC12F617T-I/SN028
PIC12F617T-I/SN030
PIC12F617T-I/SN032
PIC12F617T-I/SN038
PIC12F617T-I/SN042
PIC12F617T-I/SN043
PIC12F617T-I/SN044
PIC12F617T-I/SN045
PIC12F617T-I/SN047
PIC12F617T-I/SN048
PIC12F617T-I/SN053
PIC12F617T-I/SN059
PIC12F617T-I/SNAU
PIC12F617T-I/SNC15
PIC12F629-C/SN
PIC12F629-E/SN
PIC12F629-E/SN219
PIC12F629-E/SN244
PIC12F629-I/SN
PIC12F629-I/SN102
PIC12F629-I/SN148
PIC12F629-I/SN206
PIC12F629-I/SN207
PIC12F629-I/SN208
PIC12F629-I/SN209
PIC12F629-I/SN218
PIC12F629-I/SNC24

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
PIC12F629T-C/SN
PIC12F629T-E/SN
PIC12F629T-E/SN219
PIC12F629T-E/SN244
PIC12F629T-I/SN
PIC12F629T-I/SN039
PIC12F629T-I/SN051
PIC12F629T-I/SN056
PIC12F629T-I/SN065
PIC12F629T-I/SN069
PIC12F629T-I/SN084
PIC12F629T-I/SN091
PIC12F629T-I/SN102
PIC12F629T-I/SN138
PIC12F629T-I/SN140
PIC12F629T-I/SN148
PIC12F629T-I/SN184
PIC12F629T-I/SN211
PIC12F629T-I/SN213
PIC12F629T-I/SN214
PIC12F629T-I/SN216
PIC12F629T-I/SN220
PIC12F629T-I/SN232
PIC12F629T-I/SN233
PIC12F629T-I/SN235
PIC12F629T-I/SN241
PIC12F629T-I/SN242
PIC12F629T-I/SNC19
PIC12F635-E/SN
PIC12F635-I/SN
PIC12F635-I/SN057
PIC12F635T-I/SN
PIC12F635T-I/SN037
PIC12F635T-I/SN041
PIC12F635T-I/SN043
PIC12F635T-I/SN046
PIC12F635T-I/SN047
PIC12F635T-I/SN050
PIC12F635T-I/SN058
PIC12F635T-I/SN066
PIC12F675-C/SN
PIC12F675-E/SN
PIC12F675-I/SN

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
PIC12F675-I/SN102
PIC12F675-I/SN112
PIC12F675-I/SN166
PIC12F675-I/SN172
PIC12F675-I/SN177
PIC12F675-I/SN202
PIC12F675-I/SNC15
PIC12F675T-C/SN
PIC12F675T-E/SN
PIC12F675T-E/SN073
PIC12F675T-E/SN082
PIC12F675T-E/SN091
PIC12F675T-I/SN
PIC12F675T-I/SN026
PIC12F675T-I/SN049
PIC12F675T-I/SN075
PIC12F675T-I/SN079
PIC12F675T-I/SN085
PIC12F675T-I/SN121
PIC12F675T-I/SN131
PIC12F675T-I/SN145
PIC12F675T-I/SN150
PIC12F675T-I/SN152
PIC12F675T-I/SN153
PIC12F675T-I/SN166
PIC12F675T-I/SN172
PIC12F675T-I/SN173
PIC12F675T-I/SN178
PIC12F675T-I/SN179
PIC12F675T-I/SN185
PIC12F675T-I/SN190
PIC12F675T-I/SN191
PIC12F675T-I/SN194
PIC12F675T-I/SN195
PIC12F675T-I/SN199
PIC12F675T-I/SN200
PIC12F675T-I/SN201
PIC12F675T-I/SN202
PIC12F675T-I/SN206
PIC12F675T-I/SN207
PIC12F675T-I/SNC15
PIC12F683-E/SN
PIC12F683-E/SN083

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
PIC12F683-E/SN084
PIC12F683-I/SN
PIC12F683-I/SN075
PIC12F683-I/SNAU
PIC12F683T-E/SN
PIC12F683T-E/SN029
PIC12F683T-E/SN030
PIC12F683T-E/SN035
PIC12F683T-E/SN040
PIC12F683T-E/SN042
PIC12F683T-E/SN077
PIC12F683T-E/SN079
PIC12F683T-E/SN083
PIC12F683T-E/SN084
PIC12F683T-E/SN092
PIC12F683T-E/SN097
PIC12F683T-E/SN098
PIC12F683T-I/SN
PIC12F683T-I/SN061
PIC12F683T-I/SN062
PIC12F683T-I/SN072
PIC12F683T-I/SN091
PIC12F683T-I/SNAU
PIC12HV609-E/SN
PIC12HV609-I/SN
PIC12HV609T-I/SN
PIC12HV615-E/SN
PIC12HV615-I/SN
PIC12HV615T-E/SN
PIC12HV615T-E/SN035
PIC12HV615T-E/SN043
PIC12HV615T-E/SN044
PIC12HV615T-I/SN
PIC12HV615T-I/SN022
PIC12LC508A-04/SN
PIC12LC508A-04I/SN
PIC12LC508AT-04/SN
PIC12LC508AT-04I/SN
PIC12LC508AT-04I/SN167
PIC12LC508AT-04I/SN168
PIC12LC509A-04/SN
PIC12LC509A-04I/SN
PIC12LC509AT-04/SN

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
PIC12LC509AT-04I/SN
PIC12LC509AT-04I/SN122
PIC12LC509AT-04I/SN126
PIC12LC509AT-04I/SNG063
PIC12LF1552-E/SN
PIC12LF1552-I/SN
PIC12LF1552T-I/SN
PIC12LF1552T-I/SN021
PIC12LF1571-E/SN
PIC12LF1571-I/SN
PIC12LF1571T-I/SN
PIC12LF1571T-I/SN026
PIC12LF1571T-I/SN028
PIC12LF1572-E/SN
PIC12LF1572-I/SN
PIC12LF1572T-E/SN
PIC12LF1572T-I/SN
PIC12LF1612-E/SN
PIC12LF1612-I/SN
PIC12LF1612T-I/SN
PIC12LF1822-E/SN
PIC12LF1822-I/SN
PIC12LF1822T-E/SN
PIC12LF1822T-I/SN
PIC12LF1840-E/SN
PIC12LF1840-I/SN
PIC12LF1840T-E/SN
PIC12LF1840T-I/SN
TC1410COA
TC1410COA713
TC1410EOA
TC1410EOA713
TC1411COA
TC1411COA713
TC1411EOA
TC1411EOA713
TC1411NCOA
TC1411NCOA713
TC1411NEOA
TC1411NEOA713
TC1411NVOA
TC1411NVOA713
TC1411VOA

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
TC1411VOA713
TC1412NCOA
TC1412NCOA713
TC1412NEOA
TC1412NEOA713
TC1413NCOA
TC1413NCOA713
TC1413NEOA
TC1413NEOA713
TC1426COA
TC1426COA713
TC1427COA
TC1427COA713
TC1428COA
TC1428COA713
TC426COA
TC426COA713
TC426EOA
TC426EOA713
TC427COA
TC427COA713
TC427EOA
TC427EOA713
TC427VOA
TC427VOA713
TC428COA
TC428COA713
TC428EOA
TC428EOA713
TC428VOA
TC428VOA713
TC4420COA
TC4420COA713
TC4420EOA
TC4420EOA713
TC4420VOA
TC4420VOA713
TC4426ACOA
TC4426ACOA713
TC4426AEOA
TC4426AEOA713
TC4426AVOA
TC4426AVOA713

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
TC4426COA
TC4426COA713
TC4426COA713CAA
TC4426EOA
TC4426EOA713
TC4426VOA
TC4426VOA713
TC4427ACOA
TC4427ACOA713
TC4427AEOA
TC4427AEOA713
TC4427AEOA713AAA
TC4427AEOAAAA
TC4427AVOA
TC4427AVOA713
TC4427COA
TC4427COA713
TC4427COA713HAZ
TC4427COA723
TC4427EOA
TC4427EOA713
TC4427VOA
TC4427VOA713
TC4428ACOA
TC4428ACOA713
TC4428ACOA713-GTD
TC4428AEOA
TC4428AEOA713
TC4428AVOA
TC4428AVOA713
TC4428COA
TC4428COA713
TC4428COA723
TC4428DCOA
TC4428EOA
TC4428EOA713
TC4428VOA
TC4428VOA713
TC4429COA
TC4429COA713
TC4429EOA
TC4429EOA713
TC4429EOAAAC

JAON-08BVJU876 - CCB 1835 Final Notice: Qualification of CuPdAu bond wire in selected products of the 40K, 42K, 77K, 120K, 150K, 160K and 200K wafer technologies available in 8L SOIC package at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-08BVJU876
CATALOG_PART_NBR
TC4429VOA
TC4429VOA713
TC622COA
TC622COA713
TC622EOA
TC622EOA713
TC622VOA
TC622VOA713





**MICROCHIP**

**QUALIFICATION REPORT SUMMARY**  
RELIABILITY LABORATORY

**PCN #: JAON-08BVJU876**

**Date**  
**February 28, 2017**

**Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 8L SOIC package at MMT assembly site. The selected products of the 40K, 42K, 77K, 120K, 150K and 160K wafer technologies available in 8L SOIC package at MMT assembly site will qualify by similarity.**



## **MICROCHIP**

### **PACKAGE QUALIFICATION REPORT**

**Purpose** Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 8L SOIC package at MMT assembly site. The selected products of the 40K, 42K, 77K, 120K, 150K and 160K wafer technologies available in 8L SOIC package at MMT assembly site will qualify by similarity.

**CN** ES083164  
**QUAL ID** Q17003  
**MP CODE** LEBS14C2XB04  
**Part No.** PIC12F1840-E/SN  
**Bonding No.** BDM-000984 Rev. A  
**CCB No.** 1835

#### **Package**

**Type** 8L SOIC  
**Package size** 150 mils  
**Die thickness** 15 mils  
**Die size** 89.2 x 60.5 mils

#### **Lead Frame**

**Paddle size** 95 x 158 mils  
**Material** CDA194  
**Surface** Bare Cu  
**Process** Stamped  
**Lead Lock** Yes  
**Part Number** 10100814  
**Treatment** BOT

#### **Die attach material**

**Epoxy** 8390A  
**Wire** CuPdAu wire  
**Mold Compound** G600V  
**Plating Composition** Matte Tin



# MICROCHIP PACKAGE QUALIFICATION REPORT

## Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-173900823.000	GRSM417213312.200	1651K8V
MMT-174000077.000	GRSM417213312.200	1652MMC
MMT-174000078.000	GRSM417213312.200	1652MMD

### Result

Pass     Fail     \_\_\_\_\_

8L SOIC (.150") assembled by MTAI pass reliability test per QCI-39000.  
This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020D standard.

# PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
<b>Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)</b>	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243  ( IPC/JEDEC J-STD-020D)	IPC/JEDEC C J-STD- 020D	135	0/135	Pass	

<b>Precondition Prior Perform Reliability Tests (At MSL Level 1)</b>	<b>Electrical Test</b> :+25°C,125°C and -40°C System: J750	JESD22- A113	693(0)	693	Pass	Good Devices
	Bake 150°C, 24 hrs System: CHINEE			693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	<b>Electrical Test</b> :+25°C and 125°C System: J750			0/693		

## PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
<b>Temp Cycle</b>	<b>Stress Condition:</b> (Standard) -65°C to +150°C, 500 Cycles System : TABAI ESPEC TSA-70H <b>Electrical Test:</b> + 125°C System: J750	JESD22- A104		231		Parts had been pre-conditioned at 260°C  77 units / lot
	<b>Stress Condition:</b> (Extended) -65°C to +150°C, 1000 Cycles System : TABAI ESPEC TSA-70H <b>Electrical Test:</b> + 25°C System: J750		231(0)	0/231	Pass	
	<b>Bond Strength:</b> Wire Pull (> 2.5 grams) Bond Shear (>15.00 grams)		231(0)	0/231	Pass	
			15 (0)	0/15	Pass	
			15 (0)	0/15	Pass	
<b>UNBIASED-HAST</b>	<b>Stress Condition:</b> (Standard) +130°C/85%RH, 96 hrs. System: HAST 6000X <b>Electrical Test:</b> +25°C System: J750	JESD22- A118		231		Parts had been pre-conditioned at 260°C  77 units / lot
			231(0)	0/231	Pass	
<b>HAST</b>	<b>Stress Condition:</b> (Standard) +130°C/85%RH, 96 hrs. <b>Bias Volt:</b> 5.5 Volts System: HAST 6000X <b>Electrical Test:</b> + 25°C and 125°C System: J750	JESD22- A110		231		Parts had been pre-conditioned at 260°C  77 units / lot
			231(0)	0/231	Pass	

## PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
<b>High Temperature Storage Life</b>	<b>Stress Condition:</b> Bake 175°C, 504 hrs System: SHEL LAB	JESD22- A103		45		45 units
	<b>Electrical Test</b> :+25°C and 125°C System: J750		45(0)	0/45	Pass	
<b>Bond Strength Data Assembly</b>	Wire Pull (> 2.5 grams)	M2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	JESD22- B116	30 (0) bonds	0/30	Pass	